High Voltage Transistor

NPN Silicon

Features

• Pb-Free Packages are Available



Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	350	V
Collector - Base Voltage	V _{CBO}	350	V
Emitter - Base Voltage	V _{EBO}	5.0	V
Base Current	Ι _Β	25	mA
Collector Current - Continuous	Ic	100	mA

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

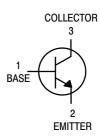
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



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SOT-23 (TO-236AB) CASE 318 STYLE 6

MARKING DIAGRAM



1Z = Device Code

M = Date Code*

= Pb-Free Package(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	<u>.</u>			•
Collector - Emitter Breakdown Voltage (I _C = 1.0 mA)	V _(BR) CEO	350	_	V
Collector - Base Breakdown Voltage (I _C = 100 μA)	V _(BR) CBO	350	-	V
Emitter - Base Breakdown Voltage (I _E = 10 μA)	V _{(BR)EBO}	6.0	-	V
Collector Cutoff Current (V _{CB} = 250 V)	Ісво	-	50	nA
Emitter Cutoff Current (V _{EB} = 5.0 V)	I _{EBO}	-	50	nA
ON CHARACTERISTICS	<u>.</u>			•
DC Current Gain $ \begin{array}{l} (I_C = 1.0 \text{ mA, } V_{CE} = 10 \text{ V}) \\ (I_C = 10 \text{ mA, } V_{CE} = 10 \text{ V}) \\ (I_C = 30 \text{ mA, } V_{CE} = 10 \text{ V}) \\ (I_C = 50 \text{ mA, } V_{CE} = 10 \text{ V}) \\ (I_C = 100 \text{ mA, } V_{CE} = 10 \text{ V}) \end{array} $	h _{FE}	20 30 30 20 15	- - 200 200 -	-
Collector – Emitter Saturation Voltage (Note 3) (I_C = 10 mA, I_B = 1.0 mA) (I_C = 20 mA, I_B = 2.0 mA) (I_C = 30 mA, I_B = 3.0 mA) (I_C = 50 mA, I_B = 5.0 mA)	V _{CE(sat)}	- - -	0.30 0.35 0.50 1.0	V
Base – Emitter Saturation Voltage (I_C = 10 mA, I_B = 1.0 mA) (I_C = 20 mA, I_B = 2.0 mA) (I_C = 30 mA, I_B = 3.0 mA)	V _{BE} (sat)	- - -	0.75 0.85 0.90	V
Base - Emitter On Voltage (I _C = 100 mA, V _{CE} = 10 V)	V _{BE(on)}	-	2.0	V
SMALL-SIGNAL CHARACTERISTICS	•		•	ı
Current Gain - Bandwidth Product (I _C = 10 mA, V _{CE} = 20 V, f = 20 MHz)	f⊤	40	200	MHz
Collector-Base Capacitance (V _{CB} = 20 V, f = 1.0 MHz)	C _{cb}	-	6.0	pF
Emitter-Base Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	C _{eb}	_	80	pF

^{3.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle = 2.0%.

ORDERING INFORMATION

Device Order Number	Package Type	Tape and Reel Size [†]	
MMBT6517LT1	SOT-23	3,000 / Tape & Reel	
MMBT6517LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel	
MMBT6517LT3	SOT-23	10,000 / Tape & Reel	
MMBT6517LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

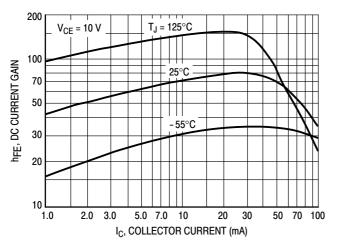


Figure 1. DC Current Gain

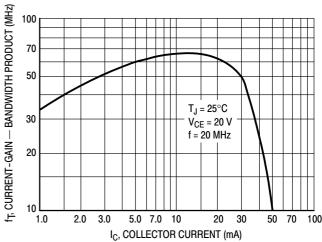


Figure 2. Current-Gain — Bandwidth Product

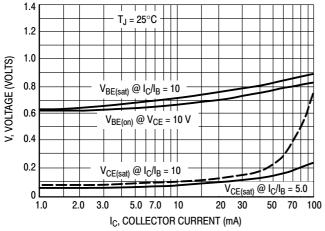


Figure 3. "On" Voltages

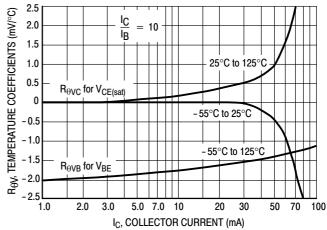


Figure 4. Temperature Coefficients

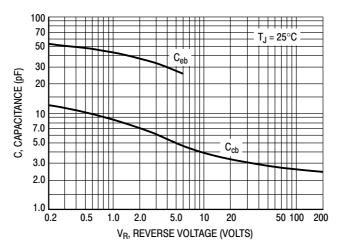


Figure 5. Capacitance

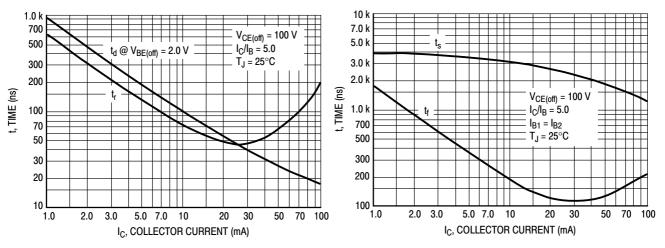


Figure 6. Turn-On Time

Figure 7. Turn-Off Time

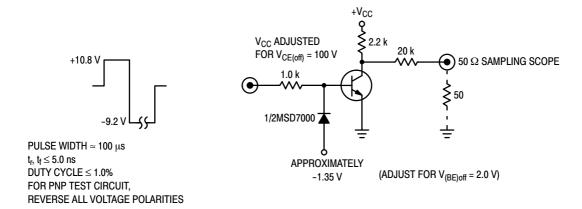


Figure 8. Switching Time Test Circuit

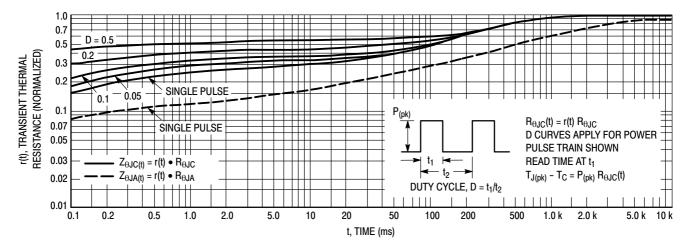
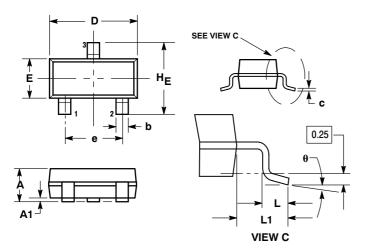


Figure 9. Thermal Response

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



NOTES

- NOTES:

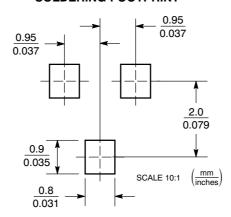
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD
- 318-08

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
Е	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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